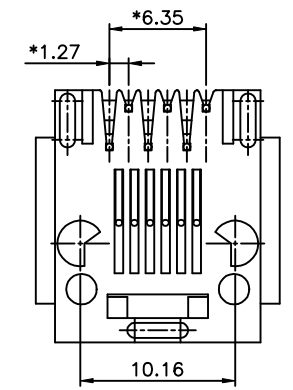
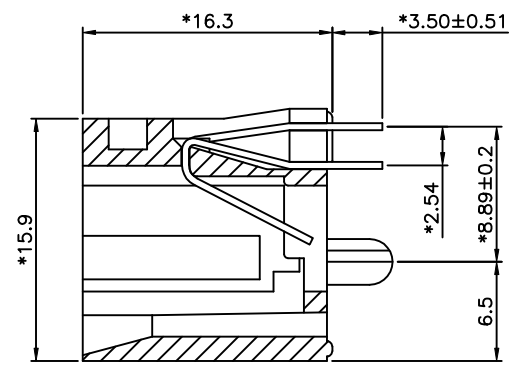
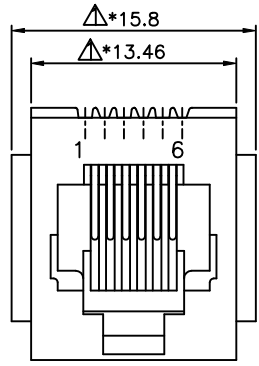


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		DRAWING MODIFY	BOYON 12/25/00	
△		ADD P/N	BOYON 06/12/02	H
△		ADD P/N	BOYON 03/08/05	
△		DEL ROHS P/N	FRACIN 5/31/05	
△		ADD&MODIFY P/N	ANKLE 08/29/05	



NOTES:

ELECTRICAL:

1. VOLTAGE RATING : 125 VAC RMS MIN.
2. CURRENT RATING : 1.5 AMP MIN.
3. CONTACT RESISTANCE : 30 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

1. HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE Ø0.46mm.
3. PLATING : GOLD PLATING OVER NICKEL.
4. OPERATING LIFE : 750 CYCLES MIN. △
5. PCB RETENTION PRE-SOLDER : 1 LB MIN.
6. PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C.
2. OPERATION: 0°C TO 70°C.

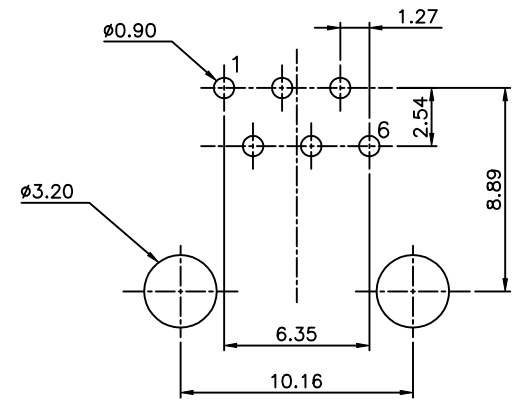
MATES WITH MODULAR PLUG CONFORMING TO

FCC PART 68, SUBPART F.

CUL FILE NO. E163191

PART NUMBER: E526X-000X1X

NO. OF CONTACTS	GOLD OF THICKNESS
2-2C	1- 3u" 2- 6u"
4-4C	3-15u" 4-30u"
6-6C	5-50u" 6-Pd 20u"
	0-PBT+15%GF BK
	D-PBT+15%GF WHITE △△
	4-PBT+15%GF GY △



PC Board Layout
Component Side Shown

DETACHED LISTS	← MM (INCH) →		DFTO SYZ	DATE 3/4/99	FULL RISE ELECTRONIC CO., LTD	
	TOLERANCES EXCEPT AS NOTED		CHKDLUXIN	DATE 2005/08/29		
	MM	±	MFO	DATE	TITLE TOP ENTRY PCB JACK 6P	
	.0 ±0.20	±	APPVLLUSHENG	DATE 2005/08/29		
.00 ±0.15	±	MATERIAL :		DRAWING NO. GE523022		
.000 ±0.075	±	ANGLES ±		/PART NO. SEE NOTE		
THIRD ANGLE PROJECTION		QT'Y :		DRAWING NO. GE523022		
		FINISH :		SIZE A3		
		SCALE : 3:1		REV 5		
				8/29/05		
			DO NOT SCALE DRAWING		SHEET X OF Y	